

Features

- Fast Switching Speed
- Power Dissipation of 200mW
- Ultra-Small Surface Mount Package
- For General Purpose Switching Applications
- High Conductance
- RoHS Compliant

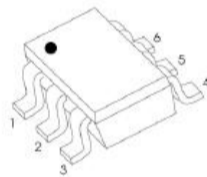
Applications

- Electronic computer
- Pulse
- Switching circuit

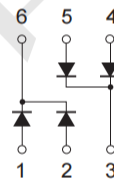
Mechanical Data

- Package: SOT-363
- Lead Finish: Matte Tin
- Case Material: "Green" Molding Compound
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020

Equivalent circuit



SOT-363



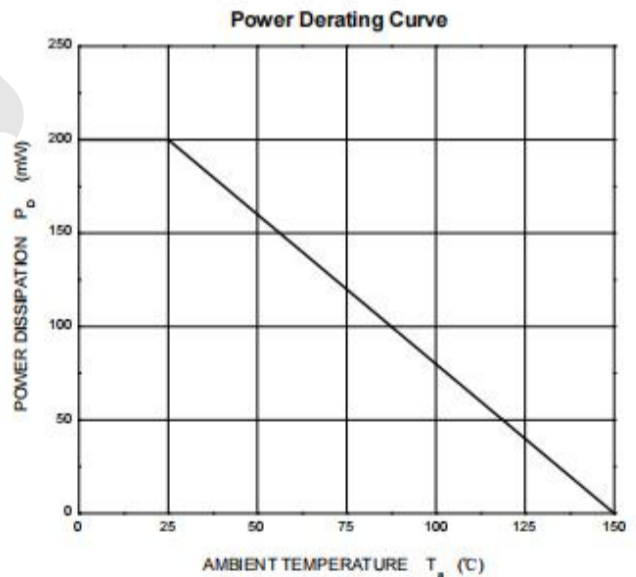
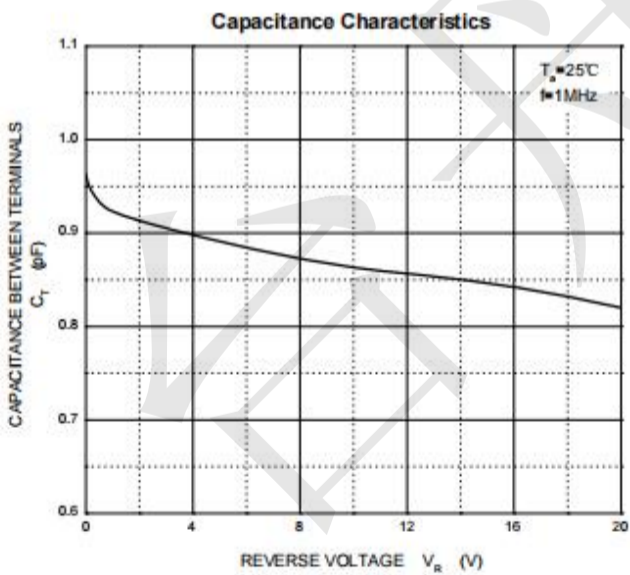
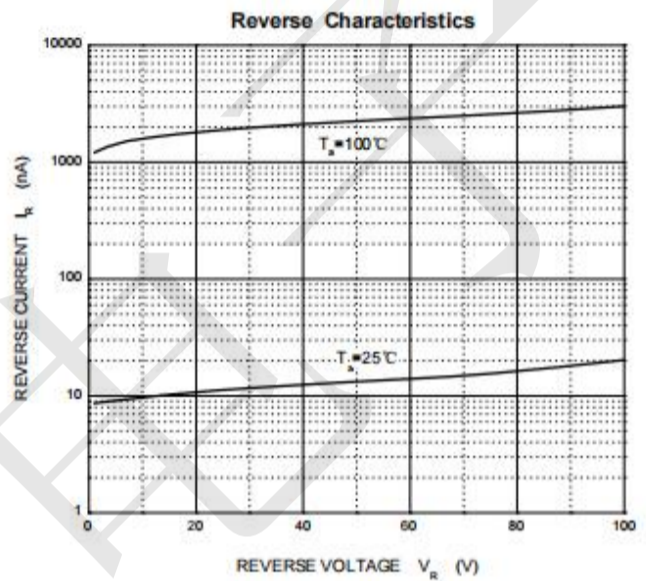
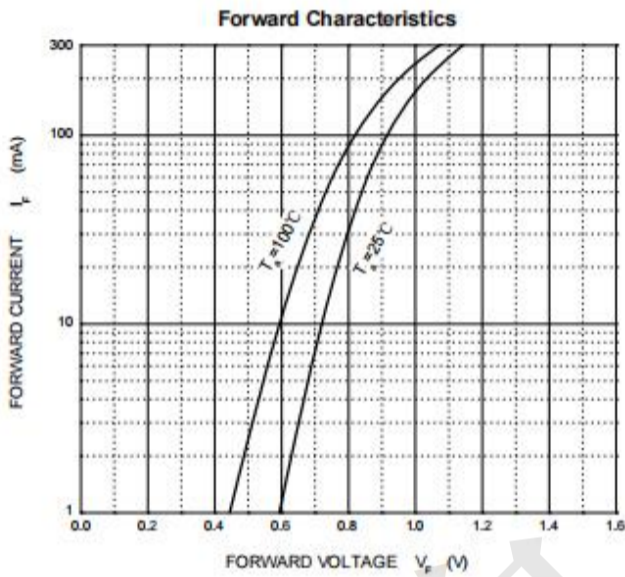
Maximum Ratings & Electrical Characteristics (TA=25°C unless otherwise noted)

| Parameter | Symbol | Value | Unit |
|---|-----------------|------------|------|
| Repetitive Peak Reverse voltage | V_{RRM} | 75 | V |
| Working Peak Reverse Voltage | V_{RWM} | 75 | V |
| Reverse voltage | V_R | 75 | V |
| Average rectified output current | I_O | 150 | mA |
| Non-repetitive peak forward current | I_{FM} | 300 | mA |
| Non-repetitive Peak Forward Surge Current @ t=8.3ms | I_{FSM} | 2 | A |
| Power Dissipation | P_D | 200 | mW |
| Thermal Resistance Junction to Ambient | $R_{\theta JA}$ | 625 | °C/W |
| Junction temperature Range | T_J | -55 ~ +150 | °C |
| Storage Temperature | T_{STG} | -55 ~ +150 | °C |

Electrical Specifications ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

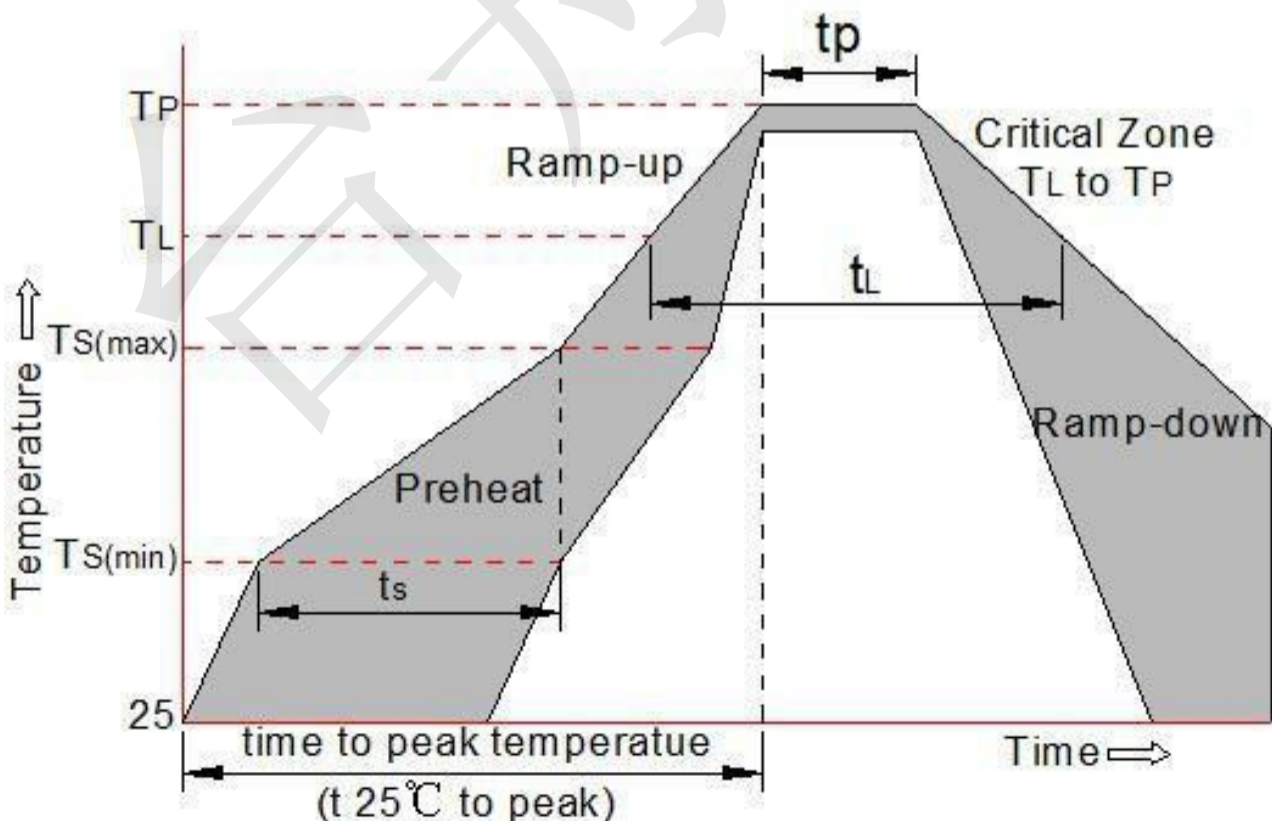
| Parameter | Symbol | Test Conditions | Limits | | Unit |
|---------------------------|----------|------------------------------|--------|-------|---------------|
| | | | Min | Max | |
| Reverse Breakdown Voltage | V_{BR} | $I_R = 2.5\mu\text{A}$ | 75 | | V |
| Reverse Leakage Current | I_R | $V_R = 20\text{V}$ | | 25 | nA |
| | | $V_R = 75\text{V}$ | | 2.5 | μA |
| Forward Voltage | V_F | $I_F = 1.0\text{mA}$ | | 0.715 | V |
| | | $I_F = 10\text{mA}$ | | 0.855 | V |
| | | $I_F = 50\text{mA}$ | | 1 | V |
| | | $I_F = 150\text{mA}$ | | 1.25 | V |
| Junction Capacitance | C_J | $V_R = 0, f = 1.0\text{MHz}$ | | 2 | pF |

Ratings and Characteristics Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

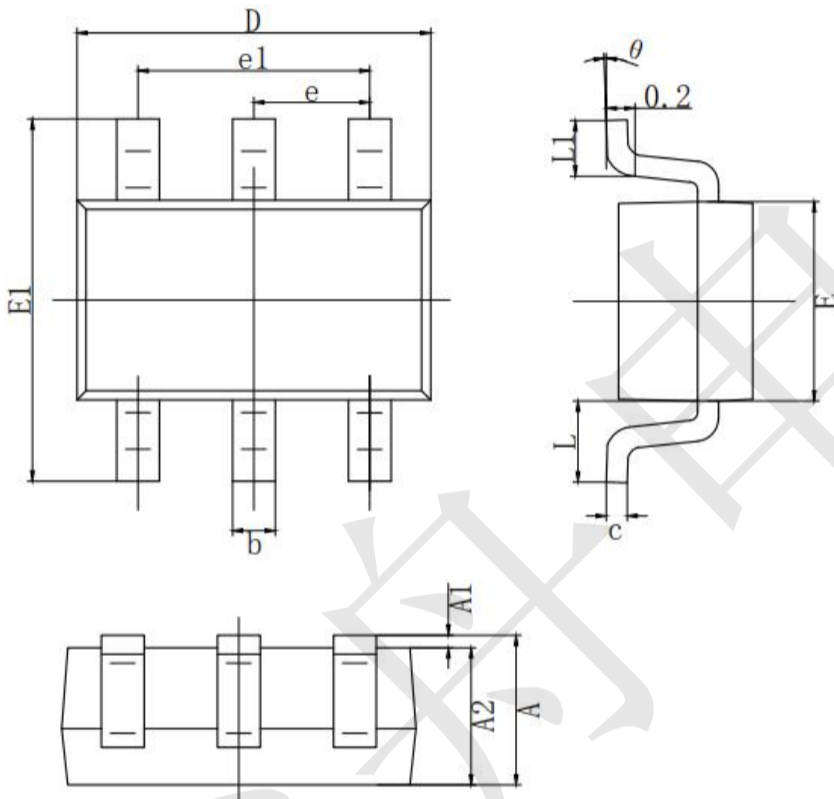


Soldering Parameters

| Reflow Condition | | Pb-Free assembly (see as bellow) |
|---|-----------------------------------|-------------------------------------|
| Pre Heat | -Temperature Min ($T_{s(min)}$) | +150 °C |
| | -Temperature Max($T_{s(max)}$) | +200 °C |
| | -Time (Min to Max) (t_s) | 60 - 180 secs. |
| Average ramp up rate (Liquid us Temp (T_L) to peak) | | 3 °C /sec. Max |
| $T_{s(max)}$ to T_L - Ramp -up Rate | | 3 °C /sec. Max |
| Reflow | -Temperature(T_L) (Liquid us) | +217 °C |
| | -Temperature(t_L) | 60 - 150 secs. |
| Peak Temp (T_p) | | +260(+0/ -5) °C |
| Time within 5 °C of actual Peak Temp (t_p) | | 30 secs. Max |
| Ramp -down Rate | | 6 °C /sec. Max |
| Time 25 °C to Peak Temp (T_p) | | 8 min. Max |
| Do not exceed | | +260 °C |



Package Outline Dimensions millimeters



| SYMBOL | MILLIMETER | |
|----------|------------|-------|
| | MIN | MAX |
| A | 0.900 | 1.100 |
| A1 | 0.000 | 0.100 |
| A2 | 0.900 | 1.000 |
| b | 0.150 | 0.350 |
| c | 0.080 | 0.150 |
| D | 2.000 | 2.200 |
| E | 1.150 | 1.350 |
| E1 | 2.150 | 2.450 |
| e | 0.650 TYP. | |
| e1 | 1.200 | 1.400 |
| L | 0.525 REF. | |
| L1 | 0.260 | 0.460 |
| θ | 0° | 8° |